

recessed portion, a non-recessed portion and opposing outer edges between the first and second surfaces that extend across the recessed and non-recessed portions, and the recessed portion is recessed relative to the non-recessed portion at the second surface, forming an encapsulant that contacts the chip, the first surface, the outer edges and the recessed portion, wherein the encapsulant completely covers the chip, the outer edges and the recessed portion without completely covering the non-recessed portion, and forming a connection joint that electrically connects the conductive trace and the pad.

In the Specification

Insert the following heading and paragraph at page 1, line 1:

CROSS-REFERENCE TO RELATED APPLICATIONS

This application is continuation of U.S. Application Serial No. 10/042,812 filed on January 9, 2002.